

Low Pass Filter

SXLP-EDU1583

Surface Mount

Important Note

This model has been designed, built and tested in our engineering department. Performance data represents model capability. At present it is a non-catalog model. On request, we can supply a final specification sheet, part number and price/delivery information.



Please click "Back", and then click "Contact Us" for Applications support.

CASE STYLE : HF1139

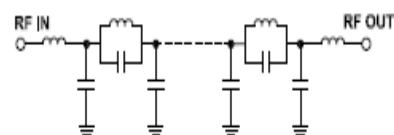
ELECTRICAL SPECIFICATIONS 50Ω @ +25°C

Parameter	Min.	Typ.	Max.	Units
Passband (Loss < 2 dB)	DC		135	MHz
Insertion loss 3 dB		143		MHz
Stopband (Loss > 20 dB)		158	1000	MHz
(Loss > 40 dB)		185	1000	MHz
Passband VSWR		1.5		(:1)
Stopband VSWR		15		(:1)

Functional Schematic

MAXIMUM RATINGS

Operating Temperature	-40°C to 85°C
Storage Temperature	-55°C to 100°C
RF Power Input	200mW



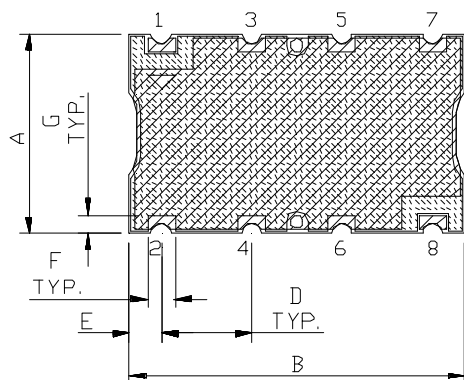
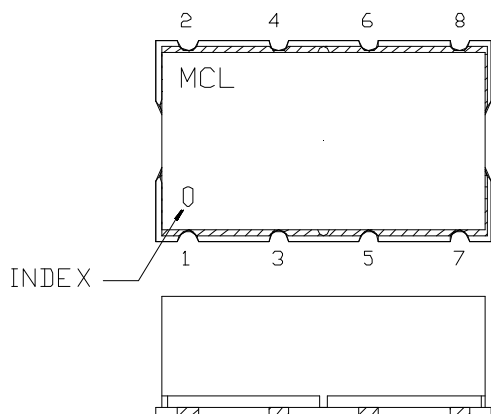
PIN CONNECTIONS

Input	1
Output	8
Ground	2,3,4,5,6,7

Typical Performance Data

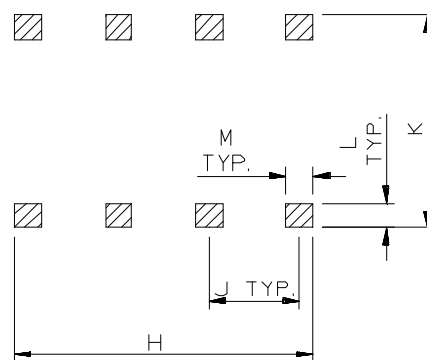
FREQUENCY (MHz)	INSERTION LOSS (dB)	RETURN LOSS (dB)	FREQUENCY (MHz)	GROUP DELAY (nsec)
1	0.06	41.95	1	5.47
20	0.13	34.77	5	5.42
60	0.29	22.79	10	5.39
118	0.60	30.72	20	5.40
135	1.01	37.32	30	5.45
143	1.81	17.75	40	5.59
145	2.56	11.86	50	5.77
148	5.63	5.07	60	5.99
151	12.02	2.20	70	5.69
155	23.74	1.21	80	5.87
158	35.66	0.97	90	7.26
160	46.67	0.89	95	7.71
185	63.70	0.51	100	8.22
215	55.16	0.38	105	8.82
240	66.37	0.31	110	9.54
250	79.71	0.28	115	10.31
300	61.94	0.21	120	11.40
450	69.44	0.15	122	11.92
500	71.05	0.14	124	12.52
600	76.14	0.14	126	13.20
700	86.70	0.16	128	14.03
800	88.68	0.16	130	14.95
900	81.21	0.19	132	16.02
1000	83.54	0.21	135	18.25

Outline Dimensions



 METALLIZATION
 SOLDER RESIST

PCB Land Pattern



CASE #	A	B	C	D	E	F	G	H	J	K	L	M	WT. GRAMS
HF1139	.44 (11.18)	.74 (18.80)	.27 (6.86)	.200 (5.08)	.07 (1.78)	.060 (1.52)	.040 (1.02)	.660 (16.76)	.200 (5.08)	.470 (11.94)	.055 (1.40)	.060 (1.52)	3.0

Dimensions are in inches (mm). Tolerances: 2 Pl. $\pm 0.015''$; 3 Pl. $\pm 0.01''$

Notes:

- Case material: Nickel-Silver alloy.
- Base: Printed wiring laminate.
- Termination finish:
 - For RoHS Case Styles: 2-5 μ inch (.05-.13 microns) Gold over 120-240 μ inch (3.05-6.10 microns) Nickel plate.
 - For RoHS-5 Case Styles: Tin-Lead plate.



P.O. Box 350166, Brooklyn, New York 11235-0003 (718) 934-4500 Fax (718) 332-4661 For detailed performance specs & shopping online see Mini-Circuits web site

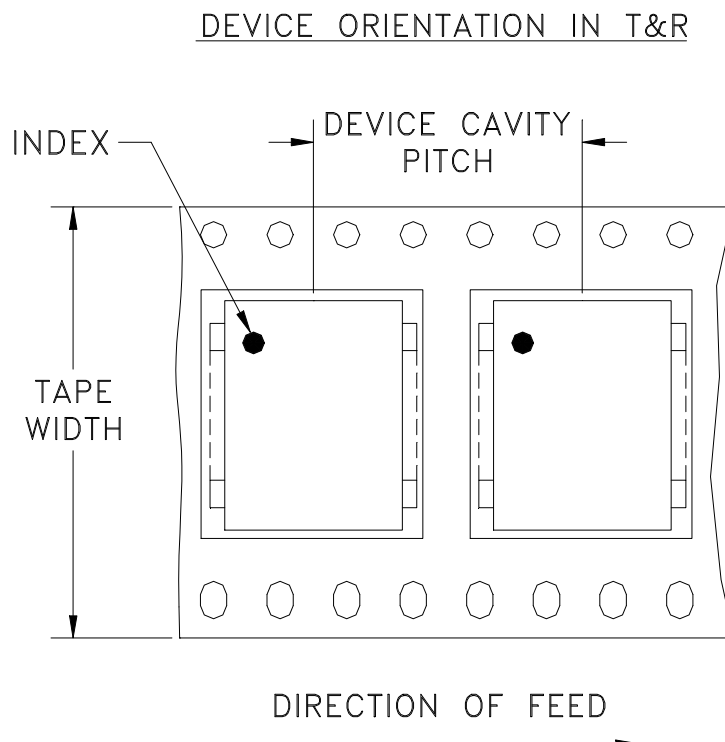


The Design Engineers Search Engine Provides ACTUAL Data Instantly From MINI-CIRCUITS At: www.minicircuits.com

RF/IF MICROWAVE COMPONENTS



Tape & Reel Packaging TR-F5



Tape Width, mm	Device Cavity Pitch, mm	Reel Size, inches	Devices per Reel
32	16	13	500

Mini-Circuits carrier tape materials provide protection from ESD (Electro-Static Discharge) during handling and transportation. Tapes are static dissipative and comply with industry standards EIA-481/EIA-541.

Go to: www.minicircuits.com/pages/pdfs/tape.pdf



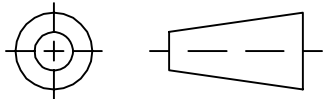
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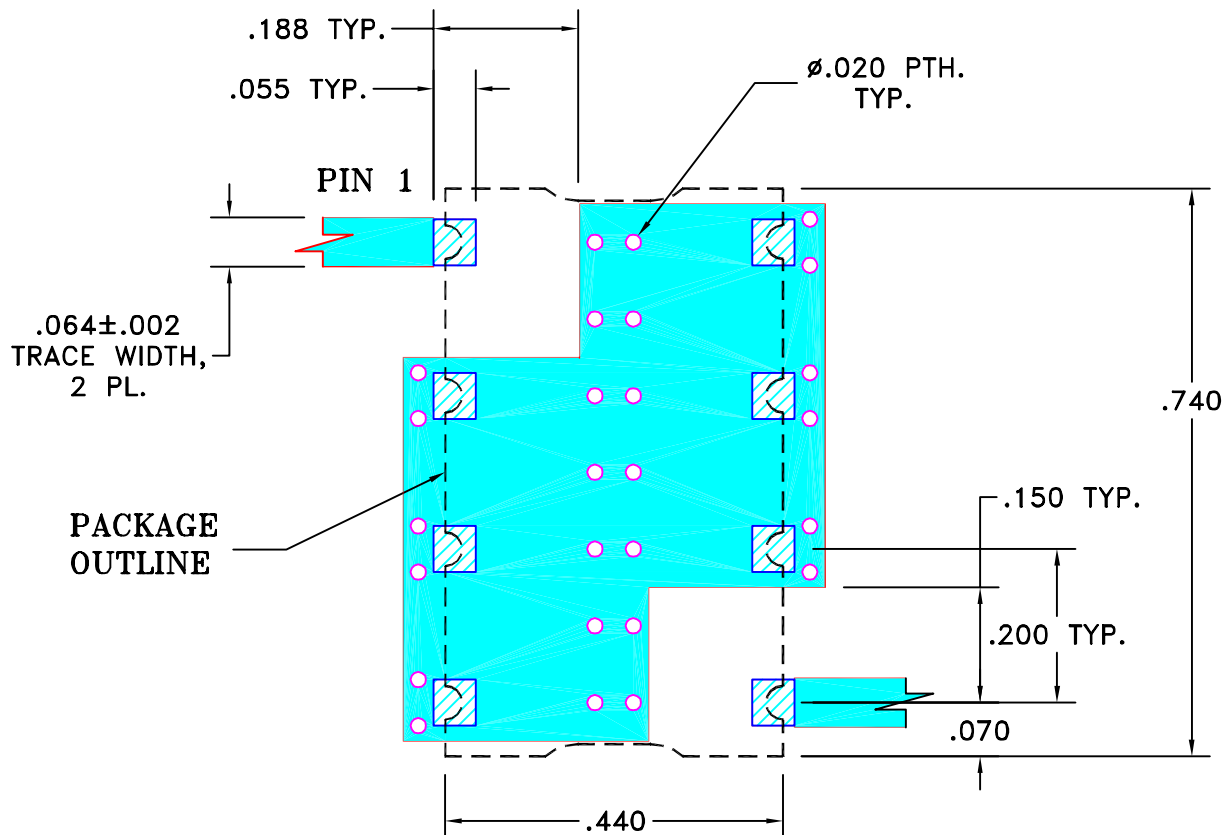
THIRD ANGLE PROJECTION



REVISIONS

REV	ECN No.	DESCRIPTION	DATE	DR	AUTH
OR	M101757	NEW RELEASE (FROM RAVON)	11/05	DK	HH
OR	R62293	NEW RELEASE (FROM RAVON)	11/05	DK	HH

SUGGESTED MOUNTING CONFIGURATION
FOR HF1139 CASE STYLE, cr PIN CONNECTION, 50 OHM.



NOTE:

1. TRACE WIDTH IS SHOWN FOR FR4 WITH DIELECTRIC THICKNESS: $.025 \pm .002$ ". COPPER: 1/2 OZ. EACH SIDE.
FOR OTHER MATERIALS TRACE WIDTH MAY NEED TO BE MODIFIED.
2. BOTTOM SIDE OF THE PCB IS CONTINUOUS GROUND PLANE.



DENOTES PCB COPPER LAYOUT WITH SMOBC (SOLDER MASK OVER BARE COPPER)



DENOTES COPPER LAND PATTERN FREE OF SOLDER MASK

UNLESS OTHERWISE SPECIFIED

INITIALS

DATE

DIMENSIONS ARE IN INCHES

TOLERANCES ON:

2 PL DECIMALS \pm 3 PL DECIMALS \pm .005ANGLES \pm FRACTIONS \pm

DRAWN

DK (RAVON)

29 NOV 05

CHECKED

RZ (RAVON)

29 NOV 05

APPROVED

HH (RAVON)

29 NOV 05



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PL, cr, HF1139, SCLF, TB-368

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SIZE

A

CODE IDENT

15542

DRAWING NO:

98-PL-230

REV:

OR

FILE:

98PL230

SCALE:

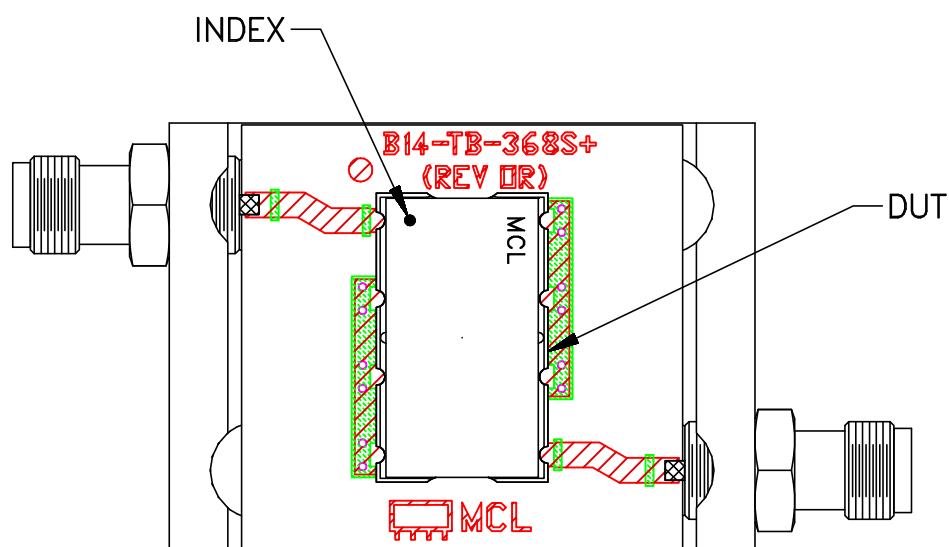
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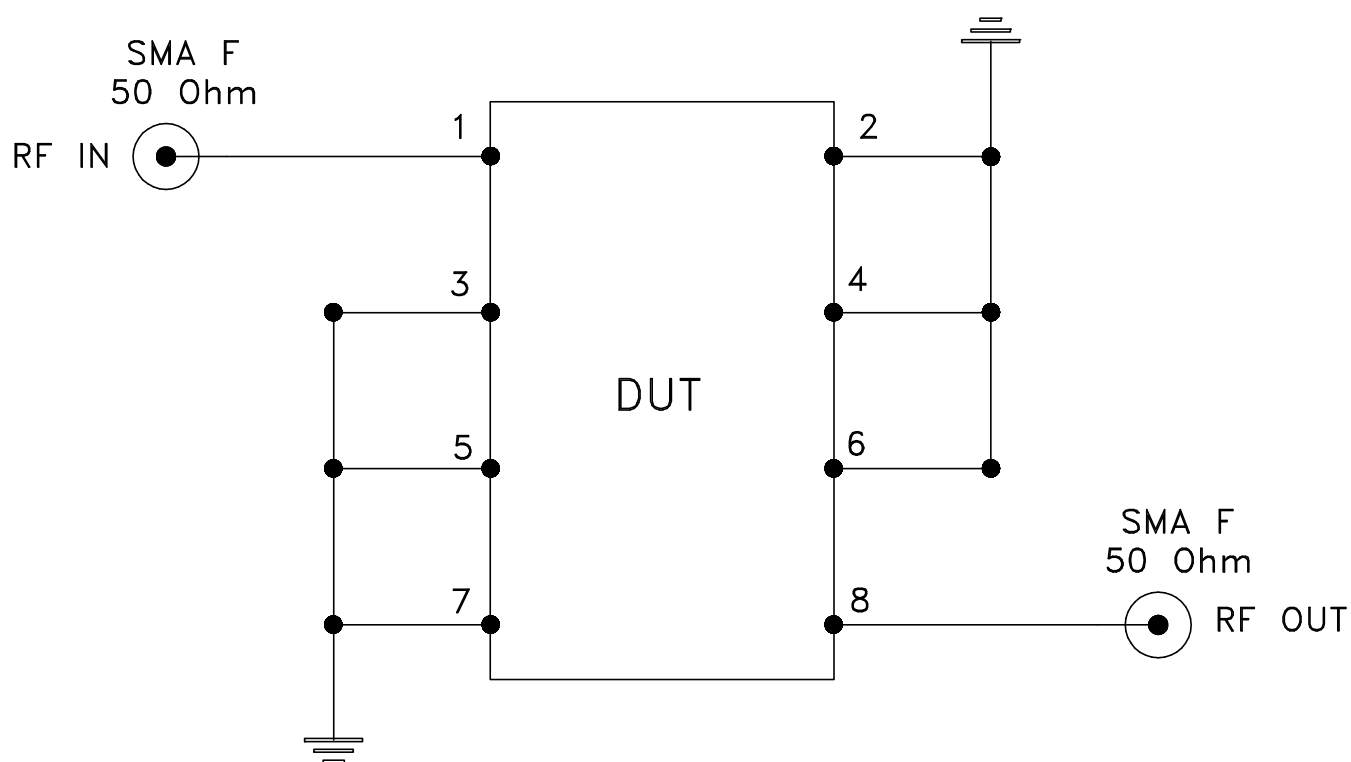
1 OF 1

ASHEETA1.DWG REV:A DATE:01/12/95

Evaluation Board and Circuit




TB-368



Schematic Diagram

Notes:

1. SMA Female connectors.
2. PCB Material: ROGERS R04350B or equivalent, Dielectric Constant=3.5, Thickness=.030 inch.

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All Mini-Circuits products are manufactured under exacting quality assurance and control standards, and are capable of meeting published specifications after being subjected to any or all of the following physical and environmental test.

Specification	Test/Inspection Condition	Reference/Spec
Operating Temperature	-40° to 85°C Ambient Environment	Individual Model Data Sheet
Storage Temperature	-55° to 100° C Ambient Environment	Individual Model Data Sheet
Humidity	90 to 95% RH, 240 hours, 50°C	MIL-STD-202, Method 103, Condition A, Except 50°C and end-point electrical test done within 12 hours
Thermal Shock	-55° to 100°C, 100 cycles	MIL-STD-202, Method 107, Condition A-3, except +100°C
Solder Reflow Heat	Sn-Pb Eutetic Process: 225°C peak Pb-Free Process 245° - 250°C peak	J-STD-020, Table 4-1, 4-2 and 5-2, Figure 5-1
Solderability	10X Magnification	J-STD-002, 95% Coverage
Vibration (High Frequency)	20g peak, 10-2000 Hz, 12 times in each of three perpendicular directions (total 36)	MIL-STD-202, Method 204, Condition D
Mechanical Shock	50g, 11 ms, 1/2-sine, 18 shocks: 3 each direction, each of 3 axes	MIL-STD-202, Method 213, Condition A
Marking Resistance to Solvents	Isopropyl alcohol + mineral spirits at 25°C; terpene defluxer at 25°C; distilled water + proylene glycol monomethyl ether + monoethanolamine at 63°C to 70°C	MIL-STD-202, Method 215